IBM

Highlights

- Award-winning design optimizing efficiencies in energy, cooling and density for data centers
- Operational costs drastically reduced based on innovative shallow depth server form factor
- High performance computing embracing broad, flexible portfolio of offerings with simplified system management and tools.



IBM System x iDataPlex dx360 M3

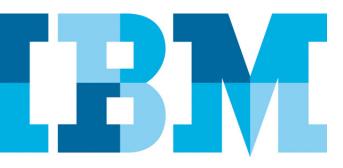
Leading the server industry in energy, cooling and space efficiencies for data centers

Designed for data centers that require high performance, yet are constrained on floor space, power and cooling infrastructure, the IBM® System x® iDataPlex® dx360 M3 provides an innovative, half-depth solution optimized for maximum density and incredible efficiency. Featuring the latest Intel® Xeon® Processor 5600 series with 16 DDR-3 DIMM sockets and two PCIe x16 Gen 2 slots, the dx360 M3 is easy to manage and delivers outstanding performance in a flexible platform that can be tailored to your data center's processing, storage or I/O needs.

For high performance computing, the dx360 M3 allows you to pack accelerated processing into the same power and cooling envelope as traditional servers, better utilizing floor space and optimizing the data center. The flexible design of the dx360 M3 integrates the right compute, storage or I/O capabilities required in your data center while optimizing density.

The innovative, shallow-depth form factor of the dx360 M3 reduces the airflow required across the components, lowering the power needed for cooling. High-efficiency power supplies, larger, better-optimized fans in the 2U chassis, and power management capabilities provide further efficiencies to minimize the dx360 M3's power requirements.

The dx360 M3 is simple to manage on a server level or at a rack level as part of an iDataPlex rack. IBM ToolsCenter provides common management across all System x servers, making the dx360 M3 easy to incorporate into your data center.



IBM System x iDataPlex dx360 M3 at a glance	
Form factor/height	Half-depth, 2U Flex chassis or 3U storage chassis
Processor (max)	Intel® Xeon® 5600 series up to 3.06 GHz (6-core) or 3.20 GHz (4-core)
Number of processors (std/max)	2 CPU, 2 GPU adapters (optional)
Cache (max)	4 MB to 12 MB
Memory (max)	Up to 192 GB DDR-3 1333 MHz via 16 DIMM slots
Expansion slots	Up to 2 slots PCle x16 electrical/x16 mech (Gen 2), 2 x8 PCle
Disk bays (total)	Up to 8 2.5" (2U) or 12 3.5" (3U storage density)
Maximum internal storage	24.0 TB (3U storage chassis)
Interconnect Fabric Adapters	Ethernet — Integrated 1 Gb dual-port Ethernet, 10 Gb (optional); Fibre Channel — 8 GB dual-port HBA (optional); InfiniBand — QDR or DDR single- or dual-port HCA (optional); solid-state drives — 160 or 320 GB High IOPS PCIe (optional)
Power supply (std/max)	900 W high efficiency nonredundant (per two servers) 550 W high efficiency nonredundant (per two servers) 750 W N+N redundant (per two servers)
Hot-swap components	Hot-swap HDDs in 3U storage dense configuration
RAID support	RAID-0, -1, -5, -6, -10, -50, -60 via optional I/O controller
Systems management	IBM Systems Director including IBM Systems Director Active Energy Manager™, Integrated Management Module (IMM) with optional remote KVM support, integrated 10/100 configurable management port
Operating systems	Red Hat Enterprise Linux® versions 6, 5 and 4, SUSE Linux Enterprise Server versions 11 and 10, Microsoft® Windows Server 2008 R2, 2008 (Datacenter, HPC, Enterprise and Web), VMware Infrastructure 3.5 and VMware vSphere 4.1
Limited warranty	3-year customer replaceable unit and onsite limited warranty



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